

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2024/0237235 A1 Xue et al.

Jul. 11, 2024 (43) **Pub. Date:**

(54) ELECTRONIC ASSEMBLY AND **ELECTRONIC DEVICE**

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18/002,199 (21) Appl. No.:

PCT Filed: Aug. 19, 2022

(86) PCT No.: PCT/CN2022/113649

> § 371 (c)(1), (2) Date:

Dec. 16, 2022

(30)Foreign Application Priority Data

Dec. 8, 2021 (CN) 202123069685.X (CN) 202123228824.9 Dec. 21, 2021

Publication Classification

(51) Int. Cl.

H05K 5/00 (2006.01)H05K 1/02 (2006.01)H05K 13/00 (2006.01)

(52) U.S. Cl.

CPC H05K 5/003 (2013.01); H05K 1/0277 (2013.01); H05K 5/0065 (2013.01); H05K 13/0015 (2013.01); H05K 2201/10083 (2013.01); H05K 2201/1009 (2013.01); H05K 2201/10121 (2013.01); H05K 2201/10151 (2013.01)

(57)ABSTRACT

An electronic assembly includes a first electronic component, a second electronic component, and a primary circuit board. The first electronic component is provided with a first secondary circuit board, the second electronic component is provided with a second secondary circuit board, the first secondary circuit board is electrically connected to the primary circuit board by using a first electrical connector, interlayer space is formed between the first secondary circuit board and the primary circuit board, a portion of the second secondary circuit board that enters the interlayer space overlaps the first secondary circuit board and is electrically connected to the primary circuit board by using a second electrical connector, the first electrical connector is located between the first secondary circuit board and the primary circuit board, and the second electrical connector is located between the second secondary circuit board and the primary circuit board.

